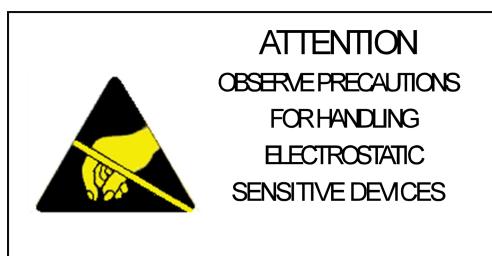


WCN-3020PG-120-8E

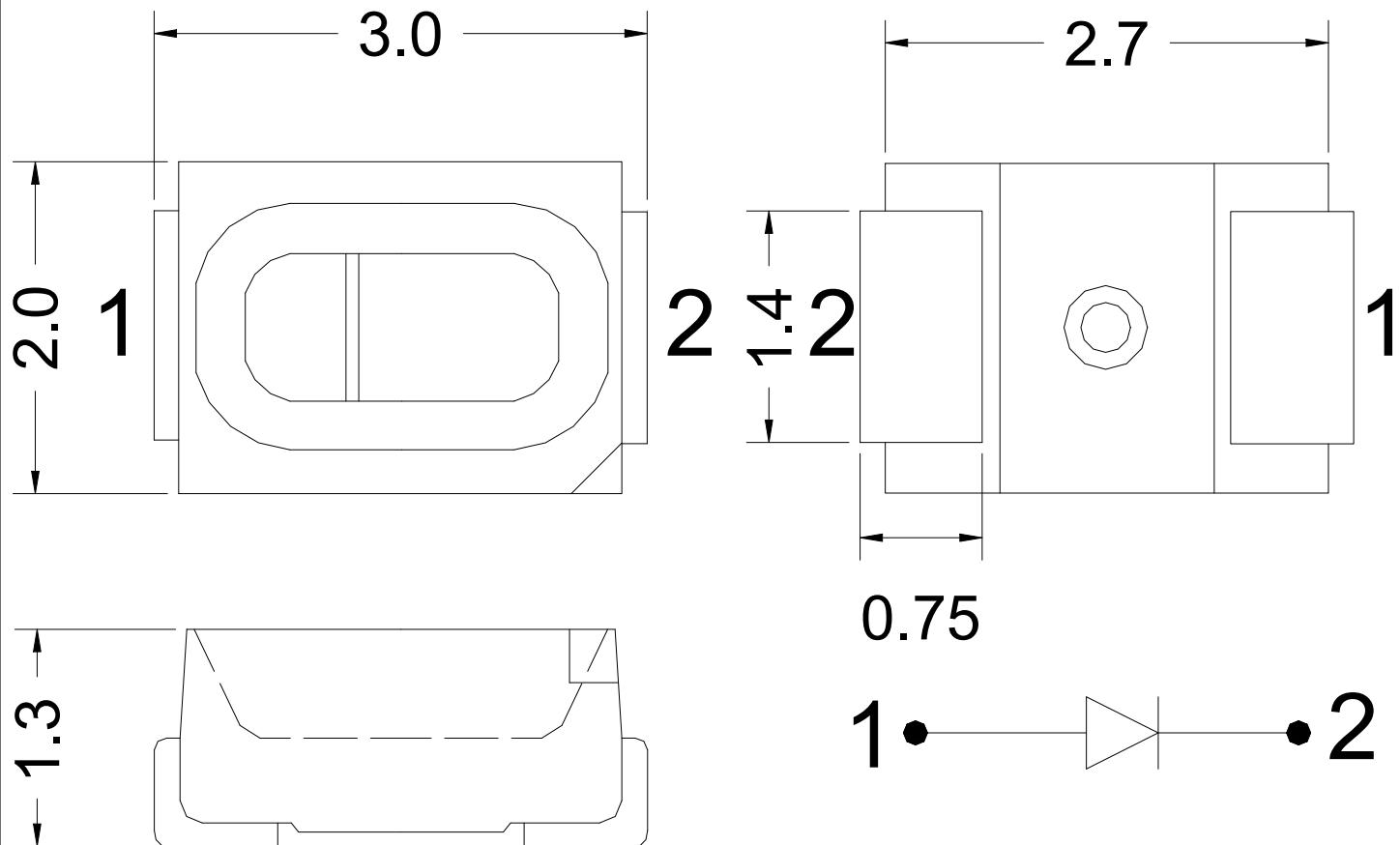
SPECIFICATION

| WCN | | | CUSTOMER Confirmed |
|---------------------|------------------------|---|-----------------------|
| Prepared by | Checked by | Approved by | |
| LiuGuo 2018-11-9 | ZhangChun 2018-11-9 |  | |



Description

- ◆ Viewing angle:120 deg
- ◆ The materials of the LED dice is InGaN
- ◆ 3.0mm×2.0mm×1.3mm
- ◆ RoHS compliant lead-free soldering compatible

Package Outline**NOTES:**

1. All dimensions units are millimeters ;
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.

Absolute Maximum Ratings at Ta=25°C

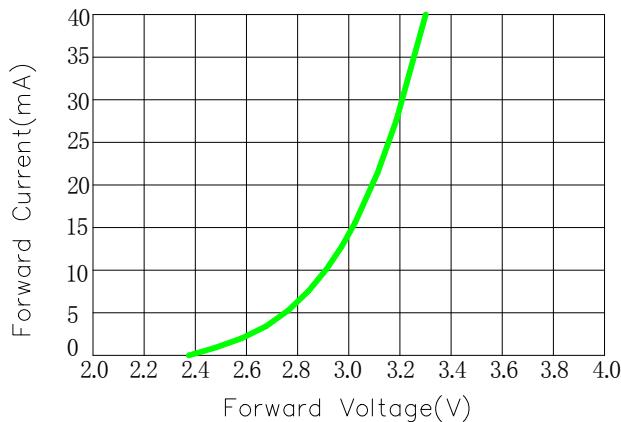
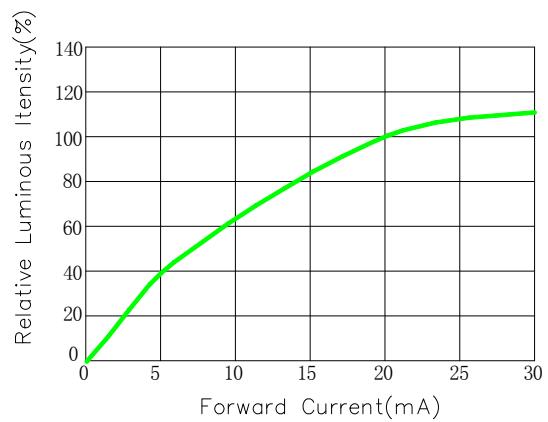
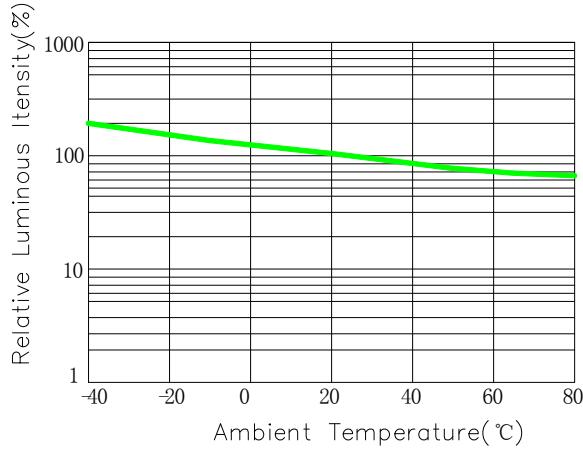
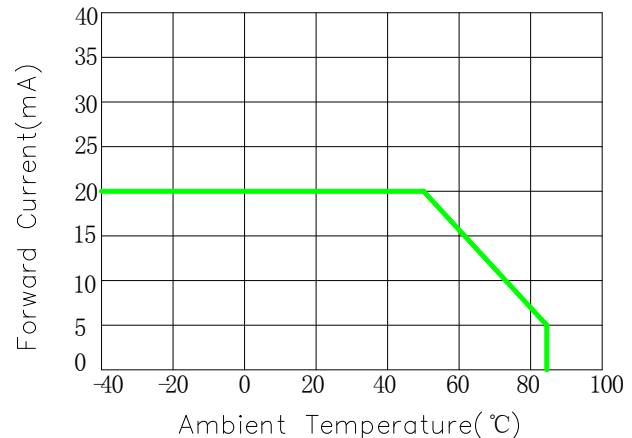
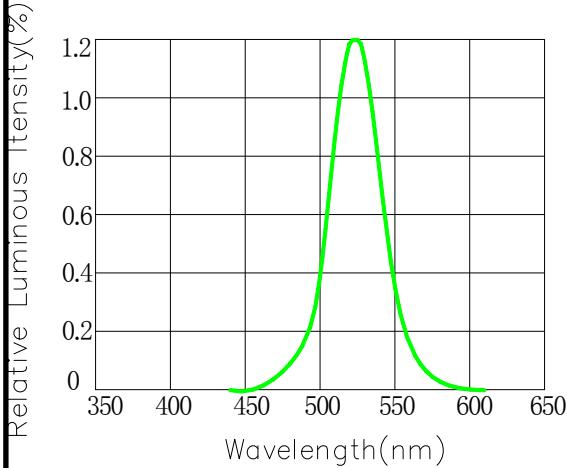
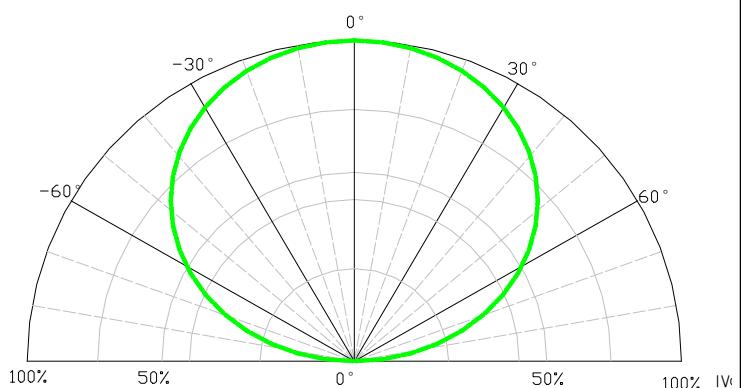
| Parameter | Symbol | Rating | Units |
|-------------------------|--------|-----------|-------|
| Power Dissipation | Pd | 102 | mW |
| Forward current | If | 30 | mA |
| Peak Forward Current | IFP | 100 | mA |
| Reverse voltage | VR | 5 | V |
| Electrostatic Discharge | ESD | 1000 | V |
| Operating temperature | Topr | -30~+85 | °C |
| Storage temperature | Tstg | -40 ~+100 | °C |
| junction temperature | Tj | 95 | °C |

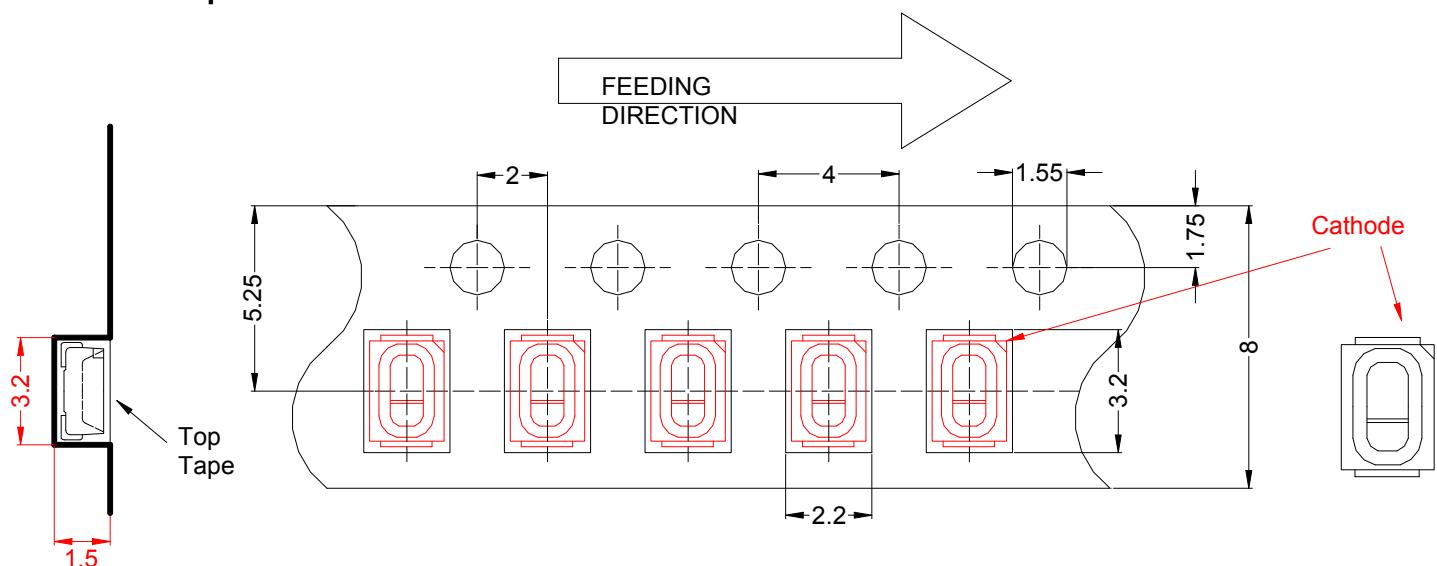
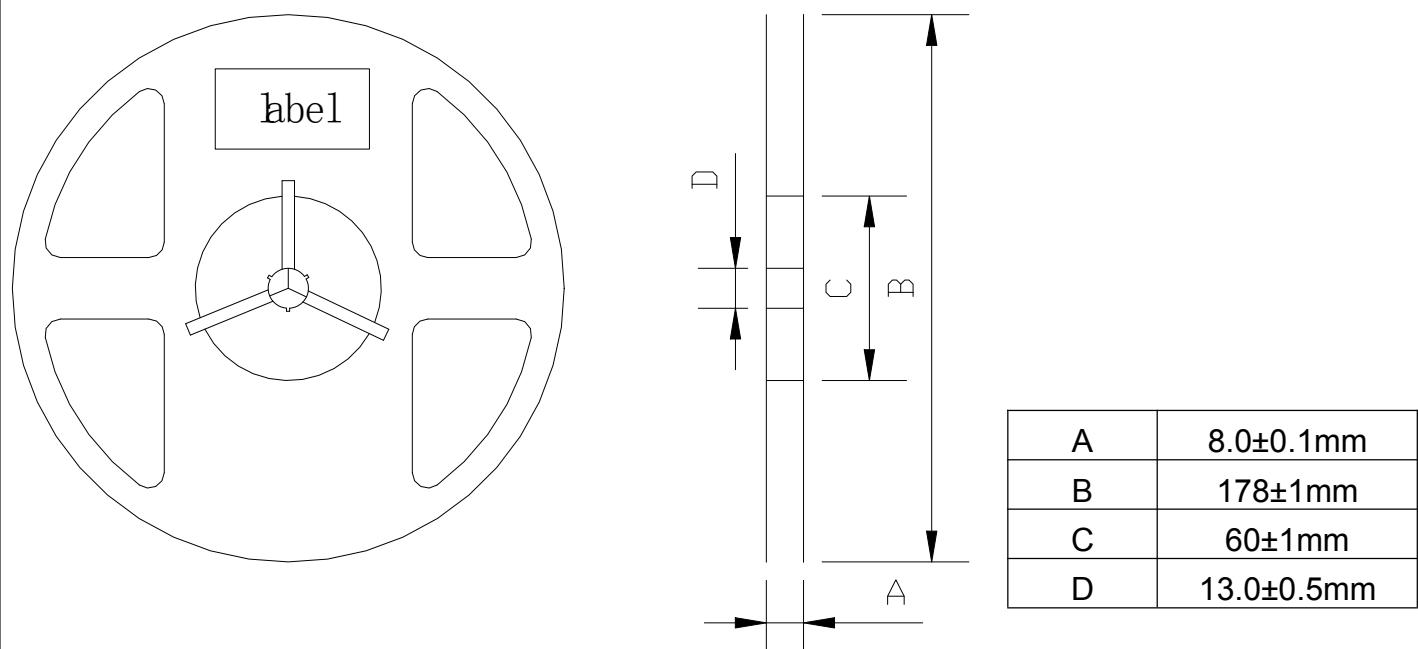
Electrical/Optical characteristics at Ta=25°C

| Item | test condition | Symbol | Value | | | Unit |
|-------------------------|----------------|--------|-------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Forward voltage | If=20mA | Vf | 2.8 | -- | 3.0 | V |
| | | | 3.0 | -- | 3.2 | V |
| | | | 3.2 | -- | 3.4 | V |
| Luminous intensity | If=20mA | Iv | 1400 | -- | 1800 | mcd |
| | | | 1800 | -- | 2400 | mcd |
| | | | 2400 | -- | 3200 | mcd |
| Dominant wavelength | If=20mA | λd | 515 | -- | 520 | nm |
| | | | 520 | -- | 525 | nm |
| | | | 525 | -- | 530 | nm |
| Reverse current | Vr=5V | Ir | -- | -- | 10 | μA |
| Viewing angle at 50% Iv | If=20mA | 2θ1/2 | -- | 120 | -- | Deg |

NOTE:

- 1.1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is 0.1V.
3. the above luminous intensity measurement allowance tolerance ±10%.

Optical characteristics curves**Forward Current VS Forward Voltage****Relative Flux VS Forward Current****Relative Flux VS Ambient Temperature****Forward Current VS Ambient Temperature****Relative Spectral Distribution****Typical Spectral Distribution**

Packaging Specifications**■ Carrier Tape Dimensions****■ Reel Dimension****NOTE:**

1. The tolerances unless mentioned $\pm 0.1\text{mm}$. Unit : mm
2. 3,000 pcs/Reel.

■ Label Form Specification

WCN Opto Group Co., Ltd

P/N:



ROHS

QTY: PCS



IV:

WL:

VF:

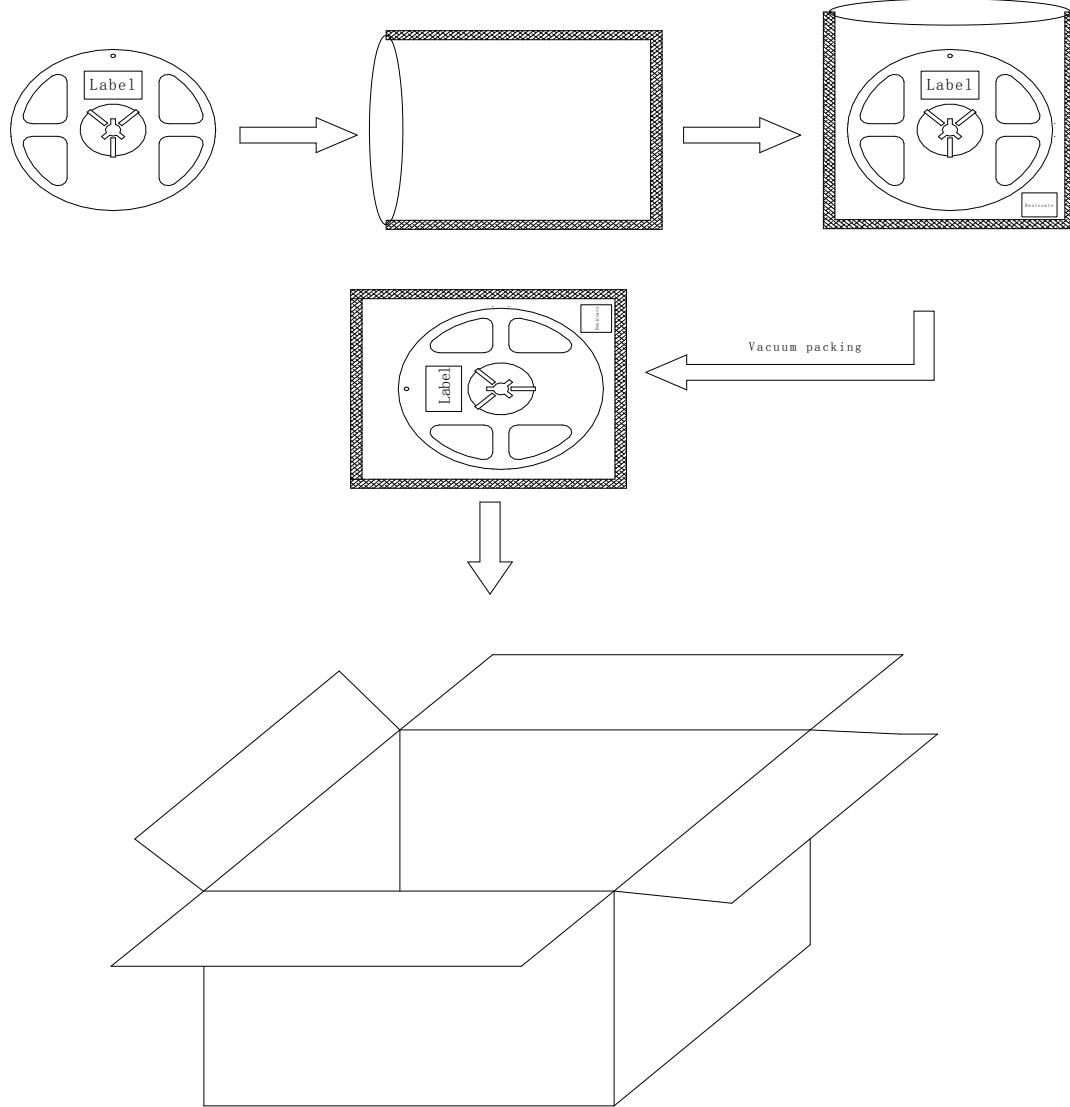
LOT NO:



MADE IN CHINA

| | |
|--------|---------------------|
| P/N | Part Number |
| QTY | Packing Quantity |
| LOT NO | Made Date |
| IV | Luminous intensity |
| WL | Dominant wavelength |
| VF | Forward Voltage |

■ Moisture Resistant Packing Process

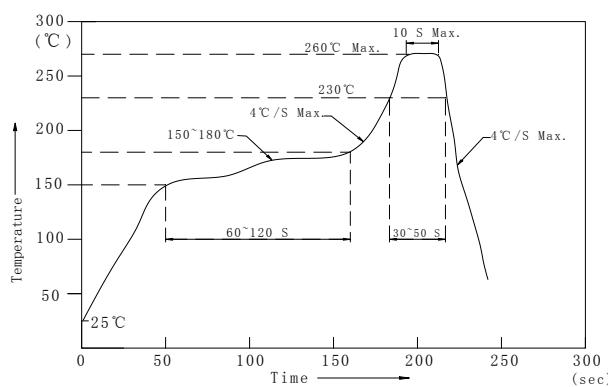


Test items and results of reliability

| Type | Test Item | Test Conditions | Note | Number of Damaged |
|------------------------|------------------------------|-----------------------------------|-----------|-------------------|
| Environmental Sequence | Reflow | Ta=260°C max T=10s | 2 times | 0/22 |
| | Temperature Cycle | -40°C 30min ↑ 100°C 30min | 100 cycle | 0/22 |
| | Thermal Shock | -40°C 15min ↑ 100°C 15min | 100 cycle | 0/22 |
| | High Humidity Heat Cycle | 30°C ⇄ 65°C 90%RH 24hrs/1cycle | 10 cycle | 0/22 |
| | High Temperature Storage | Ta=100°C | 1000 hrs | 0/22 |
| | Low Temperature Storage | Ta=-40°C | 1000 hrs | 0/22 |
| | Humidity Heat Storage | Ta=60°C RH=90% | 1000 hrs | 0/22 |
| | Low Temperature Storage | Ta=-30°C | 1000 hrs | 0/22 |
| Operation Sequence | Life Test | Ta=25°C IF=20mA | 1000 hrs | 0/22 |
| | High Humidity Heat Life Test | 60°C RH=90% IF=10mA | 500 hrs | 0/22 |
| | Low Temperature Life Test | Ta=-20°C IF=20mA | 1000 hrs | 0/22 |

Reflow Profile

■ Reflow Temp/Time



Notes:

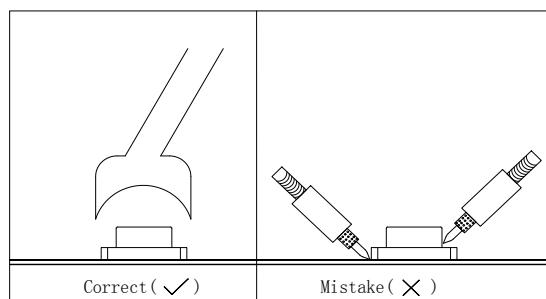
1. We recommend the reflow temperature $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$. the maximum soldering temperature should be limited to 260°C .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■ Soldering iron

Basic spec is $\leq 5\text{ sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{ sec}$). Power dissipation of iron should be smaller than 20W , and temperatures should be controllable .Surface temperature of the device should be under 230°C .

■ Rework

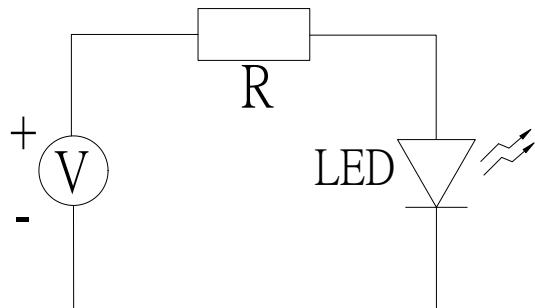
1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.

Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°C~30°C(41°F~86°F)

2.2 Shelf life in sealed bag: 12 month at <5°C~30°C and <30% R.H. After the package is

Opened, the products should be used within a week or they should be keeping to stored at ≤ 20 R.H. with zip-lock sealed.

3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as

followings:

3.1 $70\pm3^\circ\text{C}$ x(12~24hrs) and <5%RH, taped reel type

3.2 $100\pm3^\circ\text{C}$ x(45min~1hr), bulk type

3.3 $130\pm3^\circ\text{C}$ x(15~30min), bulk type